# **Presettable Counters**

# **High-Performance Silicon-Gate CMOS**

The MC74HC161A and HC163A are identical in pinout to the LS161 and LS163. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

The HC161A and HC163A are programmable 4-bit binary counters with asynchronous and synchronous reset, respectively.

#### **Features**

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 192 FETs or 48 Equivalent Gates
- These are Pb-Free Devices



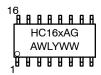
### ON Semiconductor®

http://onsemi.com

#### MARKING DIAGRAMS



SOIC-16 D SUFFIX CASE 751B





TSSOP-16 DT SUFFIX CASE 948F



c = 1 or 3

A = Assembly Location

WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 13 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

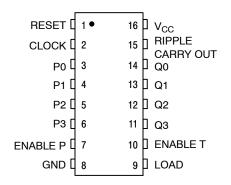


Figure 1. Pin Assignment

#### **FUNCTION TABLE**

		Output			
Clock	Reset*	Load	Enable P	Enable T	Q
\	Г	Х	Х	Х	Reset
	Н	L	×	X	Load Preset Data
_	Н	Н	Н	Н	Count
	Н	Н	L	X	No Count
	Н	Н	X	L	No Count

\*HC163A only. HC161A is an Asynchronous Reset Device H = high level, L = low level, X = don't care

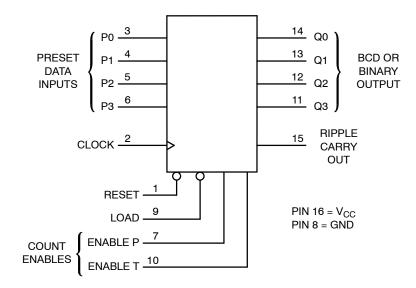


Figure 2. Logic Diagram

### **DEVICE/MODE TABLE**

Device	Count Mode	Reset Mode
HC161A	Binary	Asynchronous
HC163A	Binary	Synchronous

#### **MAXIMUM RATINGS**

Symbol	F	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		-0.5 to V <sub>CC</sub> +0.5	V
Vo	DC Output Voltage	(Note 1)	$-0.5 \le V_{O} \le V_{CC} + 0.5$	V
I <sub>IK</sub>	DC Input Diode Current		±20	mA
I <sub>OK</sub>	DC Output Diode Current		±25	mA
I <sub>O</sub>	DC Output Sink Current		±25	mA
I <sub>CC</sub>	DC Supply Current per Supply Pin		±50	mA
I <sub>GND</sub>	DC Ground Current per Ground Pin		±50	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
TL	Lead Temperature, 1 mm from Case f	or 10 Seconds	260	°C
TJ	Junction Temperature Under Bias		+150	°C
$\theta_{JA}$	Thermal Resistance	SOIC TSSOP	112 148	°C/W
$P_{D}$	Power Dissipation in Still Air at 85°C	SOIC TSSOP	500 450	mW
MSL	Moisture Sensitivity		Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 30% - 35%	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3)	> 2000 > 200	V
I <sub>LATCHUP</sub>	Latchup Performance	Above V <sub>CC</sub> and Below GND at 85°C (Note 4)	±300	mA

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1.  $I_{O}$  absolute maximum rating must be observed.
- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to EIA/JESD78.

### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Min	Max	Unit	
V <sub>CC</sub>	DC Supply Voltage	(Referenced to GND)	2.0	6.0	V
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage	(Referenced to GND)	0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature, All Package Types		<b>- 55</b>	+ 125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Figure 4)	$V_{CC} = 2.0 \text{ V}$ $V_{CC} = 3.0 \text{ V}$ $V_{CC} = 4.5 \text{ V}$ $V_{CC} = 6.0 \text{ V}$	0 0 0	1000 600 500 400	ns

5. Unused inputs may not be left open. All inputs must be tied to a high- or low-logic input voltage level.

# DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

				Guar	anteed Lim	it	
Symbol	Parameter	Test Conditions	v <sub>cc</sub> v	–55 to 25°C	≤ 85°C	≤ 125°C	Unit
V <sub>IH</sub>	Minimum High-Level	V <sub>out</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V	2.0	1.5	1.5	1.5	V
	Input Voltage	$ I_{out}  \leq 20 \mu\text{A}$	3.0	2.1	2.1	2.1	
			4.5	3.15	3.15	3.15	
			6.0	4.2	4.2	4.2	
V <sub>IL</sub>	Maximum Low-Level	V <sub>out</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V	2.0	0.5	0.5	0.5	V
	Input Voltage	$ I_{out}  \le 20 \mu A$	3.0	0.9	0.9	0.9	
			4.5	1.35	1.35	1.35	
			6.0	1.8	1.8	1.8	
V <sub>OH</sub>	Minimum High-Level	V <sub>in</sub> = V <sub>IH</sub> or V <sub>IL</sub>	2.0	1.9	1.9	1.9	V
	Output Voltage	$ I_{out}  \leq 20 \mu A$	4.5	4.4	4.4	4.4	
			6.0	5.9	5.9	5.9	
		$V_{in} = V_{IH} \text{ or } V_{IL} \qquad  I_{out}  \leq 3.6 \text{ mA}$	3.0	2.48	2.34	2.2	
		$ I_{out}  \le 4.0 \text{ mA}$	4.5	3.98	3.84	3.7	
		$ I_{out}  \le 5.2 \text{ mA}$	6.0	5.48	5.34	5.2	
V <sub>OL</sub>	Maximum Low-Level	$V_{in} = V_{IH}$ or $V_{IL}$	2.0	0.1	0.1	0.1	V
	Output Voltage	$ I_{out}  \leq 20 \mu A$	4.5	0.1	0.1	0.1	
			6.0	0.1	0.1	0.1	
		$V_{in} = V_{IH} \text{ or } V_{IL} $ $ I_{out}  \leq 3.6 \text{ mA}$	3.0	0.26	0.33	0.4	
		$ I_{out}  \le 4.0 \text{ mA}$	4.5	0.26	0.33	0.4	
		$ I_{out}  \le 5.2 \text{ mA}$	6.0	0.26	0.33	0.4	
l <sub>in</sub>	Maximum Input Leakage Current	V <sub>in</sub> = V <sub>CC</sub> or GND	6.0	± 0.1	± 1.0	± 1.0	μΑ
I <sub>CC</sub>	Maximum Quiescent Supply Current	$V_{in} = V_{CC}$ or GND $I_{out} = 0 \mu A$	6.0	4.0	40	160	μΑ

# AC ELECTRICAL CHARACTERISTICS ( $C_L$ = 50 pF, Input $t_r$ = $t_f$ = 6.0 ns)

			V <sub>CC</sub>	Guar	anteed Lim	nit	
Symbol	Parameter	Figure	V	– 55 to 25°C	≤ <b>85</b> °C	≤ 125°C	Unit
f <sub>max</sub>	Maximum Clock Frequency (50% Duty Cycle) (Note 6)	4, 10	2.0 3.0 4.5 6.0	6 15 30 35	5 12 24 28	4 10 20 24	MHz
t <sub>PLH</sub>	Maximum Propagation Delay, Clock to Q	4, 10	2.0 3.0 4.5 6.0	120 75 20 16	160 120 23 20	200 150 28 22	ns
t <sub>PHL</sub>		4, 10	2.0 3.0 4.5 6.0	145 100 22 18	185 135 25 20	220 150 30 23	ns
t <sub>PHL</sub>	Maximum Propagation Delay, Reset to Q (HC161A Only)	5, 10	2.0 3.0 4.5 6.0	145 100 20 17	185 135 22 19	220 150 25 21	ns
t <sub>PLH</sub>	Maximum Propagation Delay, Enable T to Ripple Carry Out	6, 10	2.0 3.0 4.5 6.0	110 60 16 14	150 115 18 15	190 140 20 17	ns
t <sub>PHL</sub>		6, 10	2.0 3.0 4.5 6.0	135 100 18 15	175 130 20 16	210 160 22 20	ns
t <sub>PLH</sub>	Maximum Propagation Delay, Clock to Ripple Carry Out	4, 10	2.0 3.0 4.5 6.0	120 75 22 18	160 135 27 22	200 150 30 25	ns
t <sub>PHL</sub>		4, 10	2.0 3.0 4.5 6.0	145 100 22 20	185 135 28 24	220 150 35 28	ns
t <sub>PHL</sub>	Maximum Propagation Delay, Reset to Ripple Carry Out (HC161A Only)	5, 10	2.0 3.0 4.5 6.0	155 120 22 18	190 140 26 22	230 155 30 25	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Transition Time, Any Output	5, 10	2.0 3.0 4.5 6.0	75 30 15 13	95 40 19 16	110 55 22 19	ns
C <sub>in</sub>	Maximum Input Capacitance	4, 10	-	10	10	10	pF

<sup>6.</sup> Applies to noncascaded/nonsynchronous clocked configurations only with synchronously cascaded counters. (1) Clock to Ripple Carry Out propagation delays. (2) Enable T or Enable P to Clock setup times and (3) Clock to Enable T or Enable P hold times determine f<sub>max</sub>. However, if Ripple Carry out of each stage is tied to the Clock of the next stage (nonsynchronously clocked) the f<sub>max</sub> in the table above is applicable. See Applications information in this data sheet.

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
C <sub>PD</sub>	Power Dissipation Capacitance (Per Gate) (Note 7)	45	pF

<sup>7.</sup> Used to determine the no–load dynamic power consumption:  $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$ .

# TIMING REQUIREMENTS ( $C_L = 50 \ pF$ , Input $t_r = t_f = 6.0 \ ns$ )

			V <sub>CC</sub>	Guar	anteed Lim	it	1
Symbol	Parameter	Figure	V	– 55 to 25°C	≤ <b>85</b> °C	≤ 125°C	Unit
t <sub>su</sub>	Minimum Setup Time,	8	2.0	40	60	80	ns
	Preset Data Inputs to Clock		3.0	20	30	40	
	·		4.5	15	20	30	
			6.0	12	18	20	
t <sub>su</sub>	Minimum Setup Time,	8	2.0	60	75	90	ns
	Load to Clock		3.0	25	30	40	
			4.5	15	20	30	
			6.0	12	18	20	
$t_{su}$	Minimum Setup Time,	7	2.0	60	75	90	ns
	Reset to Clock (HC163A Only)		3.0	25	30	40	
			4.5	20	25	35	
			6.0	17	23	25	
$t_{su}$	Minimum Setup Time,	9	2.0	80	95	110	ns
	Enable T or Enable P to Clock		3.0	35	40	50	
			4.5	20	25	35	
			6.0	17	23	25	
t <sub>h</sub>	Minimum Hold Time,	8	2.0	3	3	3	ns
	Clock to Load or Preset Data Inputs		3.0	3	3	3	
			4.5	3	3	3	
			6.0	3	3	3	
t <sub>h</sub>	Minimum Hold Time,	7	2.0	3	3	3	ns
	Clock to Reset (HC163A Only)		3.0	3	3	3	
			4.5	3	3	3	
			6.0	3	3	3	
t <sub>h</sub>	Minimum Hold Time,	9	2.0	3	3	3	ns
	Clock to Enable T or Enable P		3.0	3	3	3	
			4.5	3	3	3	
			6.0	3	3	3	
$t_{rec}$	Minimum Recovery Time,	5	2.0	80	95	110	ns
	Reset Inactive to Clock (HC161A Only)		3.0	35	40	50	
			4.5	15	20	26	
			6.0	12	17	23	
$t_{rec}$	Minimum Recovery Time,	8	2.0	80	95	110	ns
	Load Inactive to Clock		3.0	35	40	50	
			4.5 6.0	15 12	20 17	26 23	
+	Minimum Pulse Width,	4	2.0		75		no
t <sub>w</sub>	Clock		3.0	60 25	30	90 40	ns
	Clour		4.5	12	15	18	
			6.0	10	13	15	
t <sub>w</sub>	Minimum Pulse Width,	5	2.0	60	75	90	ns
VV	Reset (HC161A Only)		3.0	25	30	40	
	, ,,,		4.5	12	15	18	
			6.0	10	13	15	
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and Fall Times		2.0	1000	1000	1000	ns
	·		3.0	800	800	800	
			4.5	500	500	500	
	1	1	6.0	400	400	400	

#### **FUNCTION DESCRIPTION**

The HC161A/163A are programmable 4-bit synchronous counters that feature parallel Load, synchronous or asynchronous Reset, a Carry Output for cascading, and count-enable controls.

The HC161A and HC163A are binary counters with asynchronous Reset and synchronous Reset, respectively.

#### **INPUTS**

#### Clock (Pin 2)

The internal flip-flops toggle and the output count advances with the rising edge of the Clock input. In addition, control functions, such as resetting and loading, occur with the rising edge of the Clock input.

### Preset Data Inputs P0, P1, P2, P3 (Pins 3, 4, 5, 6)

These are the data inputs for programmable counting. Data on these pins may be synchronously loaded into the internal flip-flops and appear at the counter outputs. Po (Pin 3) is the least-significant bit and P3 (Pin 6) is the most-significant bit.

#### **OUTPUTS**

#### Q0, Q1, Q2, Q3 (Pins 14, 13, 12, 11)

These are the counter outputs. Q0 (Pin 14) is the least-significant bit and Q3 (Pin 11) is the most-significant bit.

#### **Ripple Carry Out (Pin 15)**

When the counter is in its maximum state, 1111, this output goes high, providing an external look-ahead carry pulse that may be used to enable successive cascaded counters. Ripple Carry Out remains high only during the maximum count state. The logic equation for this output is:

Ripple Carry Out = Enable T • Q0 • Q1 • Q2 • Q3

#### **OUTPUT STATE DIAGRAMS**

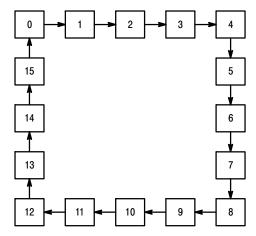


Figure 3. Binary Counters

#### **CONTROL FUNCTIONS**

#### Resetting

A low level on the Reset pin (Pin 1) resets the internal flip-flops and sets the outputs (Q0 through Q3) to a low level. The HC161A resets asynchronously, and the HC163A resets with the rising edge of the Clock input (synchronous reset).

#### Loading

With the rising edge of the Clock, a low level on Load (Pin 9) loads the data from the Preset Data input pins (P0, P1, P2, P3) into the internal flip-flops and onto the output pins, Q0 through Q3. The count function is disabled as long as Load is low.

#### Count Enable/Disable

These devices have two count-enable control pins: Enable P (Pin 7) and Enable T (Pin 10). The devices count when these two pins and the Load pin are high. The logic equation is:

#### Count Enable = Enable P • Enable T • Load

The count is either enabled or disabled by the control inputs according to Table 1. In general, Enable P is a count-enable control: Enable T is both a count-enable and a Ripple-Carry Output control.

Table 1. Count Enable/Disable

	Control Inp	uts	Result at Outputs			
Load	Enable P	Enable T	Q0 – Q3	Ripple Carry Out		
Н	Н	Н	Count	Lligh when OO OO		
L	Н	Н	No Count	High when Q0-Q3 are maximum*		
Х	L	Н	No Count	High when Q0–Q3 are maximum*		
Х	Х	L	No Count	L		

<sup>\*</sup>Q0 through Q3 are maximum when Q3, Q2, Q1, Q0 = 1111.

### **SWITCHING WAVEFORMS**

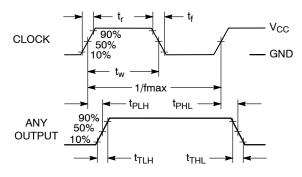


Figure 4.

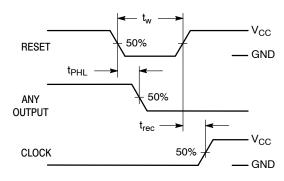


Figure 5.

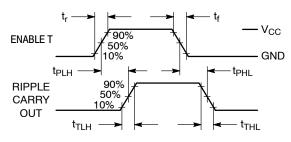


Figure 6.

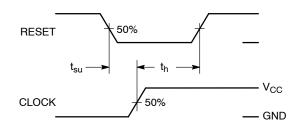


Figure 7. HC163A Only

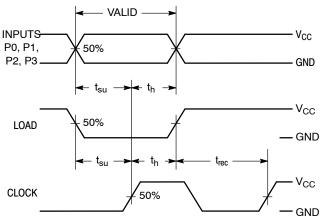


Figure 8.

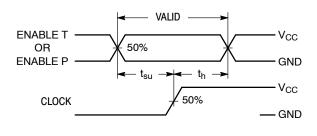
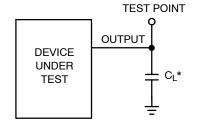


Figure 9.

### **TEST CIRCUIT**



<sup>\*</sup>Includes all probe and jig capacitance

Figure 10.

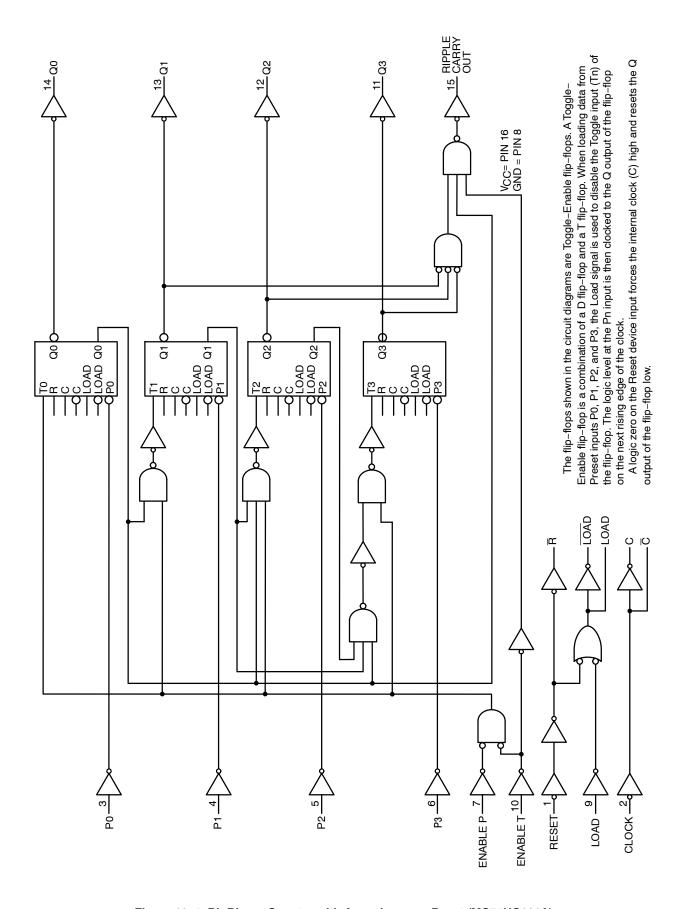


Figure 11. 4-Bit Binary Counter with Asynchronous Reset (MC74HC161A)

Sequence illustrated in waveforms:

- 1. Reset outputs to zero.
- 2. Preset to binary twelve.
- 3. Count to thirteen, fourteen, fifteen, zero, one and two.
- 4. Inhibit.

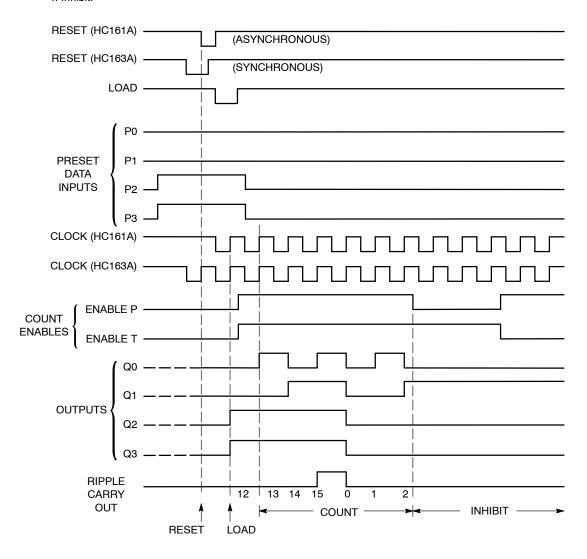


Figure 12. Timing Diagram

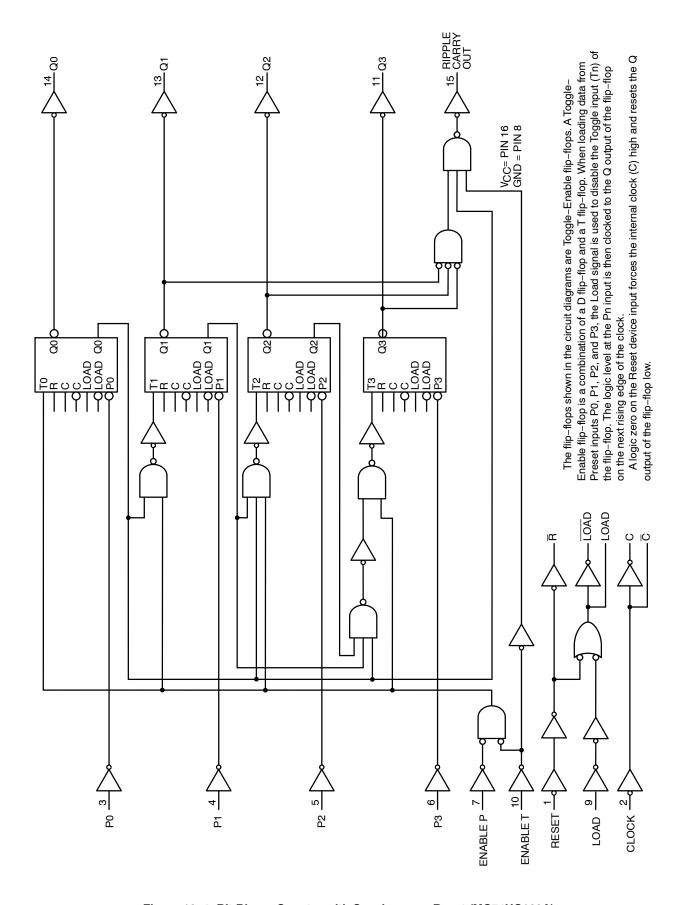
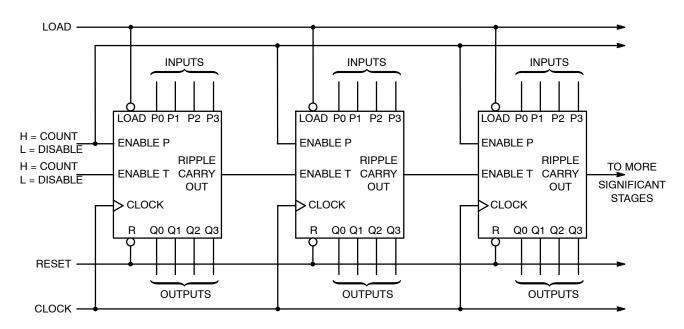


Figure 13. 4-Bit Binary Counter with Synchronous Reset (MC74HC163A)

#### TYPICAL APPLICATIONS CASCADING



NOTE: When used in these cascaded configurations the clock f<sub>max</sub> guaranteed limits may not apply. Actual performance will depend on number of stages. This limitation is due to set up times between Enable (Port) and Clock.

Figure 14. N-Bit Synchronous Counters

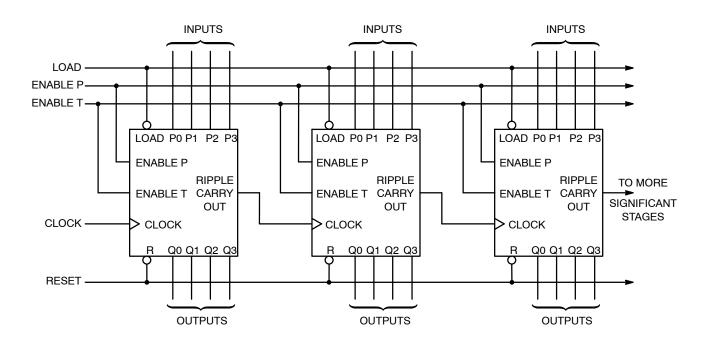


Figure 15. Nibble Ripple Counter

#### TYPICAL APPLICATIONS VARYING THE MODULUS

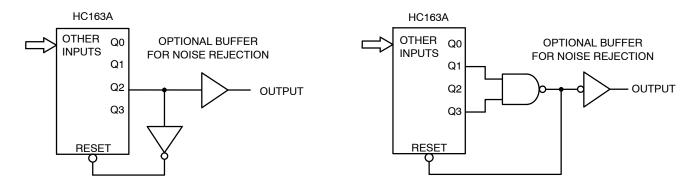


Figure 16. Modulo-5 Counter

Figure 17. Modulo-11 Counter

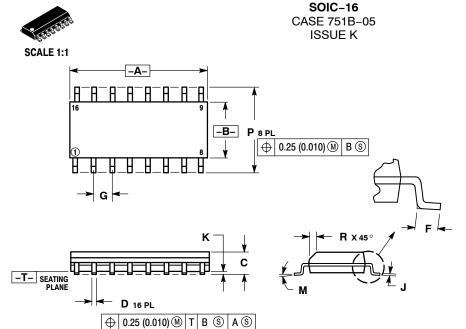
The HC163A facilitates designing counters of any modulus with minimal external logic. The output is glitch–free due to the synchronous Reset.

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74HC161ADTG	TSSOP-16 (Pb-Free)	96 Units / Tube
MC74HC163ADTG	TSSOP-16 (Pb-Free)	96 Units / Tube
MC74HC161ADG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74HC161ADR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
MC74HC161ADTR2G	TSSOP-16*	2500 Units / Tape & Reel
MC74HC163ADG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74HC163ADR2G	SOIC-16 (Pb-Free)	2500 Units / Tape & Reel
MC74HC163ADTR2G	TSSOP-16*	2500 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

<sup>\*</sup>This package is inherently Pb-Free.



**DATE 29 DEC 2006** 

- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI
- THE NOTION AND TOLETANOING FER ANSI'Y 14.5M, 1982.
  CONTROLLING DIMENSION: MILLIMETER.
  DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- PHOI HUSION.

  MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

  DIMENSION D DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR PROTRUSION

  SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D

  DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INCHES			
DIM	MIN	MAX	MIN	MAX		
Α	9.80	10.00	0.386	0.393		
В	3.80	4.00	0.150	0.157		
С	1.35	1.75	0.054	0.068		
D	0.35	0.49	0.014	0.019		
F	0.40	1.25	0.016	0.049		
G	1.27	BSC	0.050 BSC			
J	0.19	0.25	0.008	0.009		
K	0.10	0.25	0.004	0.009		
M	0°	7°	0°	7°		
Р	5.80	6.20	0.229	0.244		
R	0.25	0.50	0.010	0.019		

STYLE 1:		STYLE 2:		STYLE 3:		STYLE 4:			
PIN 1.		PIN 1.		PIN 1.	COLLECTOR, DYE #1	PIN 1.	COLLECTOR, DYE	E #1	
2.			ANODE	2.	BASE, #1	2.	COLLECTOR, #1		
3.	EMITTER	3.	NO CONNECTION	3.	EMITTER, #1	3.	COLLECTOR, #2		
4.	NO CONNECTION	4.	CATHODE	4.	COLLECTOR, #1	4.	COLLECTOR, #2		
5.	EMITTER	5.	CATHODE	5.	COLLECTOR, #2	5.	COLLECTOR, #3		
6.	BASE	6.	NO CONNECTION	6.	BASE, #2	6.	COLLECTOR, #3		
7.	COLLECTOR	7.	ANODE	7.	EMITTER, #2	7.	COLLECTOR, #4		
8.	COLLECTOR			8.	COLLECTOR, #2	8.	COLLECTOR, #4		
9.	BASE		CATHODE	9.	COLLECTOR, #3	9.	BASE, #4		
10.	EMITTER	10.	ANODE	10.	BASE, #3	10.	EMITTER, #4		
11.	NO CONNECTION	11.		11.	EMITTER, #3	11.	BASE, #3		
12.	EMITTER		CATHODE	12.		12.			
13.	BASE		CATHODE	13.	COLLECTOR, #4	13.	BASE, #2	SOI DEDING	FOOTPRINT
14.			NO CONNECTION	14.	BASE, #4	14.	EMITTER, #2	SOLDENING	FOOTFRINT
15.	EMITTER		ANODE	15.	EMITTER, #4	15.	BASE, #1	:	8X
16.	COLLECTOR	16.	CATHODE	16.	COLLECTOR, #4	16.	EMITTER, #1	6	.40
								-	0
STYLE 5:		STYLE 6:		STYLE 7:					16X 1.12 ← ➤
PIN 1.	DRAIN, DYE #1		CATHODE	PIN 1.	SOURCE N-CH				,
2.	DRAIN. #1		CATHODE	2.	COMMON DRAIN (OUTPUT	1		. 🗀 1	16
3.	DRAIN, #2		CATHODE	3.	COMMON DRAIN (OUTPUT			<b>↓</b> — ·	· · · <b></b>
4.	DRAIN, #2	4.	CATHODE	4.	GATE P-CH	,		<u>-</u>	
5.	DRAIN, #3	5.	CATHODE	5.	COMMON DRAIN (OUTPUT	1	16	6X 🛣	
6.	DRAIN, #3	6.	CATHODE	6.	COMMON DRAIN (OUTPUT		0.9		' <u> </u>
7.	DRAIN, #4	7.	CATHODE	7.	COMMON DRAIN (OUTPUT		0.	56	ı
8.	DRAIN, #4	8.	CATHODE	8.	SOURCE P-CH	•			
9.	GATE, #4	9.	ANODE	9.	SOURCE P-CH				
10.	SOURCE, #4	10.	ANODE	10.	COMMON DRAIN (OUTPUT	)			
11.	GATE, #3	11.	ANODE	11.	COMMON DRAIN (OUTPUT				
12.	SOURCE, #3	12.	ANODE	12.	COMMON DRAIN (OUTPUT				
13.	GATE, #2	13.	ANODE	13.	GATE N-CH	,			
14.	SOURCE, #2	14.	ANODE	14.	COMMON DRAIN (OUTPUT	)			V PITCH
15.	GATE, #1	15.	ANODE	15.	COMMON DRAIN (OUTPUT				<del>                                    </del>
16.	SOURCE, #1		ANODE	16.	SOURCE N-CH	•			
	- /							<b>□</b> 8	9 + - + -
									~ <b></b>
									DIMENSIONS: MILLIMETERS

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0.10 (0.004)

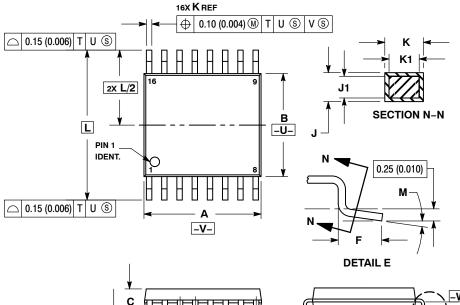
D

-T- SEATING PLANE



TSSOP-16 CASE 948F-01 ISSUE B

**DATE 19 OCT 2006** 



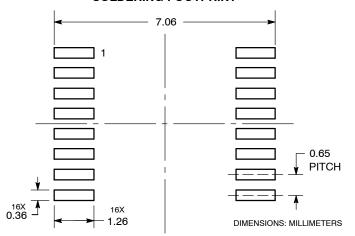
#### NOTES

- JIES:
  DIMENSIONING AND TOLERANCING PER
  ANSI Y14.5M, 1982.
  CONTROLLING DIMENSION: MILLIMETER.
  DIMENSION A DOES NOT INCLUDE MOLD
  FLASH. PROTRUSIONS OR GATE BURRS.
  MOLD EL ROLL OF GATE BURDS SUAL NO.
- MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
- DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
Κ	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
Г	6.40 BSC		0.252 BSC	
М	0 °	8 °	0 °	8 °

#### **SOLDERING FOOTPRINT**

G



#### **GENERIC MARKING DIAGRAM\***

168888888 XXXX XXXX **ALYW** 1<del>88888888</del>

XXXX = Specific Device Code Α = Assembly Location

= Wafer Lot L Υ = Year W = Work Week = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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